EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	35	("20010002858" | "20020019296" | "20020180344" | "20020180709" | "4685771" | "4688900" | "4876441" | "4948232" | "5321533" | "5333074" | "5473450" | "5530566" | "5679414" | "5751388" | "5949508" | "5978063" | "5999239" | "6019284" | "6051639" | "6128056" | "6141071" | "6195196" | "6211994" | "6284418" | "6293470" | "6310612" | "6310671" | "6311076" | "6312304" | "6316278" | "6330208" | "6335818" | "6356376" | "6362915").PN. OR ("6655788").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/01 14:48
L3	24	("20020190257" | "5107175" | "5124204" | "5189405" | "5686360" | "5693956" | "5757126" | "5771562" | "5811177" | "5882761" | "5952778" | "5973258" | "5990542" | "6146225" | "6149757" | "6150187" | "6198217" | "6198220" | "6268695" | "6274887" | "6320115" | "6323416" | "6413645" | "6445005").PN. OR ("6965195").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/01 14:56
L4	1	"7015640".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/01 16:02
L6	2585	257/40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 16:18
L7	1723	257/94	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:12

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L8	2211	257/99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:31
L9	1151	257/100	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:52
L10	3750	428/411.1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:52
S1	41	(semicondutor or die or chip or IC) with organic and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 20:46
S2	6	(semicondutor or die or chip or IC) near organic and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 20:51
S3	366	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 20:59
S4	0	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and substrate with wrap	USPAT	OR	ON	2006/07/06 20:59
S5	2	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and substrate with wrap$4	USPAT	OR	ON	2006/07/06 21:00
S6	160	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and substrate with cover$3	USPAT	OR	ON	2006/07/06 22:26

S7	0	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and "6965195".pn.	USPAT	OR	ON	2006/07/06 21:25
S8	1	"2003062527".pn. or "2002068143".pn. or "6080031". pn. or "2003104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:30
S9	1	"2003062527".pn. or "2002068143".pn. or "6080031". pn. or "2003104753".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/06 21:27
S10	1	"2003062527".pn. or "2002068143".pn. or "6080031". pn. or "2003104753".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/06 21:27
S11	0	"2003062527".pn. or "2002068143".pn. or "2003104753".pn.	US-PGPUB; USOCR	OR	ON	2006/07/06 21:27
S12	0	"2003062527".pn. or "2002068143".pn. or "2003104753".pn.	US-PGPUB	OR	ON	2006/07/06 21:28
S13	418	257/777	US-PGPUB	OR	ON	2006/07/06 21:30
S14	1	"2003/062527".pn. or "2002/068143".pn. or "6080031". pn. or "2003/104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:29
S15	1	"2003062527".pn. or "2002068143".pn. or "6080031". pn. or "2003104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:29
S16	12	"2003062527".pn. or "2002068143".pn. or "6080031". pn. or "2003104753".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 21:29
S17	4	"20030062527".pn. or "20020068143".pn. or "6080031". pn. or "20030104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:31
S18	2382	257/40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 22:06
S19	1630	257/94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 22:20

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S20	2	"6737753".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 22:20
S21	6	("5920080" | "6244441" | "6291126" | "6333537" | "6522067" | "6570325").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/06 22:25
S22	11	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and warp$4	USPAT	OR	ON	2006/07/06 23:36
S23	35	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and bend$3 with substrate	USPAT	OR	ON	2006/07/06 22:52
S24	10	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and cover$3 with (edge or perimeter) with substrate	USPAT	OR	ON	2006/07/06 22:54
S25	10	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and cover$3 with (edge or perimeter) with substrate	USPAT	OR	ON	2006/07/06 22:57
S26	35	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and cover$3 with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:01
S27	0	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and suround$3 with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:01
S28	8	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and surround$3 with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:04

S29	2	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and ("U" or "C") near shaped with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:05
S30	9	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and ("U" or "C") near shaped	USPAT	OR	ON	2006/07/06 23:10
S31	367	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 23:10
S32	41	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with transparent and fold$3	USPAT	OR	ON	2006/07/06 23:50
S33	47	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with (translucent or glass) and fold$3	USPAT	OR	ON	2006/07/07 00:06
S34	0	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible near substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 00:06
S35	0	((semicondutor or die or chip or IC or led or emitt$3) same organic or OLED) and flexible near substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 01:47
S36	0	((semicondutor or die or chip or IC or led or emitt$3) or OLED) and flexible near substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 00:06
S37	1	((semicondutor or die or chip or IC or led or emitt$3) or OLED) and flexible with substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 00:07

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S38	1	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 01:18
S39	23	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and clip	USPAT	OR	ON	2006/07/07 01:26
S40	0	((semicondutor or die or chip or IC or led or emitt$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and clip with metal	USPAT	OR	ON	2006/07/07 01:26
S41	0	((led or emitt$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and clip with metal	USPAT	OR	ON	2006/07/07 01:26
S42	1	((led or emitt$3) with organic or OLED) and flexible with substrate and clip with metal	USPAT	OR	ON	2006/07/07 01:27
S43	110	((led or emitt$3) with organic or OLED) and substrate with (clip or frame) with metal	USPAT	OR	ON	2006/07/07 01:42
S44	0	((led or emitt$3) with organic or OLED) and substrate with (clip or frame) with copper	USPAT	OR	ON	2006/07/07 01:42
S45	302	(semiconductor or die or chip) and substrate with (clip or frame) with copper	USPAT	OR	ON	2006/07/07 01:42
S46	63	(semiconductor or die or chip) and substrate with (clip) with metal	USPAT	OR	ON	2006/07/07 01:54
S47	6	(organic near optoelectronic same (organic near photovoltaic with OLED))	USPAT	OR	ON	2006/07/07 01:48
S48	0	(semiconductor or die or chip) and substrate with (clip) with metal with polyimide	USPAT	OR	ON	2006/07/07 01:55
S49	1	(semiconductor or die or chip) and substrate same clip with metal with polyimide	USPAT	OR	ON	2006/07/07 01:56
S50	4	(semiconductor or die or chip) and substrate same clip with metal with rubber	USPAT	OR	ON	2006/07/07 01:56

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S51	4	(semiconductor or die or chip) and substrate same clip with metal with polymer	USPAT	OR	ON	2006/07/07 01:58
S52	0	(semiconductor or die or chip) and substrate same flexible near frame with metal with polymer	USPAT	OR	ON	2006/07/07 01:58
S53	0	(semiconductor or die or chip) and substrate and flexible near frame with metal with polymer	USPAT	OR	ON	2006/07/07 02:01
S54	5	(semiconductor or die or chip) and substrate and clip with metal with polymer	USPAT	OR	ON	2006/07/07 01:58
S55	2	(semiconductor or die or chip) and substrate and flexible near frame with metal with (polymer or rubber or polyimide)	USPAT	OR	ON	2006/07/07 02:02
S56	0	(semiconductor or die or chip) and substrate and flexible near frame with foil with (polymer or rubber or polyimide)	USPAT	OR	ON	2006/07/07 02:02
S57	2	(semiconductor or die or chip) and substrate and clip with foil with (polymer or rubber or polyimide)	USPAT	OR	ON	2006/07/07 02:05
S58	2	(semiconductor or die or chip) and substrate and clip with foil with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:12
S59	3	(semiconductor or die or chip) and substrate and clamp with foil with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:05
S60	29	(semiconductor or die or chip) and substrate and clip with metal with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:12
S61	4	(semiconductor or die or chip) and substrate and clip with made with metal with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:13
S62	9	(semiconductor or die or chip) and substrate and clip with formed with metal with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:17
S63	13	(semiconductor or die or chip) and substrate and clip with formed with metal with (plastic)	USPAT	OR	ON	2006/07/07 02:17